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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Miwa KOZAWA et al.**

Art Unit: **1795**

Application Number: **10/670,291**

Examiner: **Daborah Chacko-Davis**

Filed: **September 26, 2003**

Confirmation Number: **6427**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR FORMING
RESIST PATTERN, AND PROCESS FOR MANUFACTURING
SEMICONDUCTOR DEVICE**

Attorney Docket Number: **031181**

Customer Number: **38834**

AMENDMENT

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

June 23, 2009

Sir:

This paper is filed in response to the Office Action dated March 23, 2009.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims begin on page 3 of this paper.

Remarks begin on page 12 of this paper.